

SEMICONDUCTOR INTEGRATED CIRCUIT

ABSTRACT

In a semiconductor integrated circuit (100) having a shielding film (1) formed by a material different from at least either of a semiconductor substrate (4) and an interlayer insulating film (7) in thermal expansion coefficient, the shielding film (1) has shielding portions (9) and openings (12), and at least either of a plurality of independent openings (12a) whose circumferences are surrounded by the shielding portions (9) and a plurality of independent shielding portions (11) whose circumferences are surrounded by the openings (12) is present and scattered on the entire surface of a chip. Or, a plurality of openings (12) are present on an optional straight line parallel with the surface (4a) of the semiconductor substrate (4) passing through a portion for shielding circuit devices (21) and circuit wirings (16) in the shielding portions (9).

Reference Drawing: Fig. 1

Figure 1